November 2013 Newsletter

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Or email Tom at toconnor@dfrsolutions.com.
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DfR Solutions Launching Two New Consortia

We are in the development stages for two new consortium projects:

- Quantifying Mitigation Strategies for Pb-free Assemblies: Transitioning to Printed Electronics
- Quantifying Mitigation Strategies for Pb-free Assemblies: Effect of Potting and Coatings

Stay tuned for more details over the next several weeks. If you think your company would be interested in participating in a consortium, contact Craig Hillman.

Cleanliness and Contamination Concerns

Contamination and cleanliness is believed to be one of the primary drivers of field issues in electronics today. It is a pervasive problem that will continue to get worse if requirements are not detailed to the supply chain and validated. This presentation, Contamination and Cleanliness Challenges, by Cheryl Tulkoff of DfR Solutions, was recently presented at the IPC Conference on Solder and Reliability Materials, Processes, and Tests, this paper on Contamination and Cleanliness Challenges addresses. Contact Cheryl if you have any questions or comments regarding this important topic.
Understanding the Criticality of Stencil Aperture Design for a QFN Package

Proper apertures and solder paste deposition controls are vital to the successful implementation of QFN packages, particularly those having dual rows of I/O pins. DFR worked with Microsemi to develop a successful configuration for their 164 pin 13 x 13 mm Dual row QFN. The assessment involved TherMoiré analyses to determine package warping characteristics, cross sectional analyses, and bond line thickness measurements all designed to identify the best manufacturing specifications for the package. This presentation delineates the analysis. For more information, please contact Greg Caswell.

Nanocoating for Medical Devices

In the Medical device field, there is a significant opportunity for performance improvement and cost reduction through the use of nanocoatings. However, this requires a knowledge of the materials and processes on the markets along with their risks and benefits. Read the presentation, Using Nanocoatings: Opportunities & Challenges for Medical Devices given by Cheryl Tulkoff at a recent SMTA meeting.

Other Interesting Items

Read Craig Hillman’s article, Understanding Plated Through Via Failures in the November issue of Global SMT & Packaging News.

IPC Conference to “clean up” reliability problems, Global SMT & Packaging, Tuesday, October 29, 2013

Although no-clean practices have altered printed board manufacturing processes, reliability expert Cheryl Tulkoff warns that, “Everyone should be thinking about cleaning and contamination issues.” Tulkoff, DFR Solutions, is among the experts who will address the wide range of factors impacting reliability at the IPC Conference on Solder and Reliability: Materials, Processes and Tests, November 13–14 in Costa Mesa, Calif. Read More

If you missed the following webinars, not to worry. You can view the recording and the slides below.

Introduction to Design for Reliability Thursday, November 14, 2013

View the Presentation